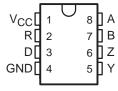
SLLS003E - OCTOBER 1985 - REVISED JUNE 1998

- Meets or Exceeds the Requirements of TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendation V.11
- Bus Voltage Range . . . –7 V to 12 V
- Positive- and Negative-Current Limiting
- Driver Output Capability . . . 60 mA Max
- Driver Thermal-Shutdown Protection
- Receiver Input Impedance . . . 12 kΩ Min
- Receiver Input Sensitivity . . . ±200 mV
- Receiver Input Hysteresis . . . 50 mV Typ
- Operates From Single 5-V Supply
- Low Power Requirements

D OR P PACKAGE (TOP VIEW)



description

The SN75179B is a differential driver and receiver pair designed for balanced transmission-line applications and meets TIA/EIA-422-B, TIA/EIA-485-A, and ITU Recommendation V.11. It is designed to improve the performance of full-duplex data communications over long bus lines.

The SN75179B driver output provides limiting for both positive and negative currents. The receiver features high input impedance, input hysteresis for increased noise immunity, and input sensitivity of ± 200 mV over a common-mode input voltage range of -7 V to 12 V. The driver provides thermal shutdown for protection from line fault conditions. Thermal shutdown is designed to occur at a junction temperature of approximately 150°C. The SN75179B is designed to drive current loads of up to 60 mA maximum.

The SN75179B is characterized for operation from 0°C to 70°C.

Function Tables

DRIVER

INPUT	OUT	PUTS
D	Υ	Z
Н	Н	L
L	L	Н

RECEIVER

DIFFERENTIAL INPUTS A – B	OUTPUT R
V _{ID} ≥ 0.2 V	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$?
$V_{ID} \le -0.2 V$	L
Open	?

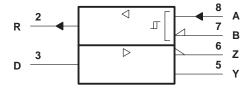
H = high level, L = low level, ? = indeterminate



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

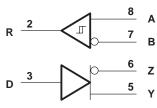


logic symbol[†]

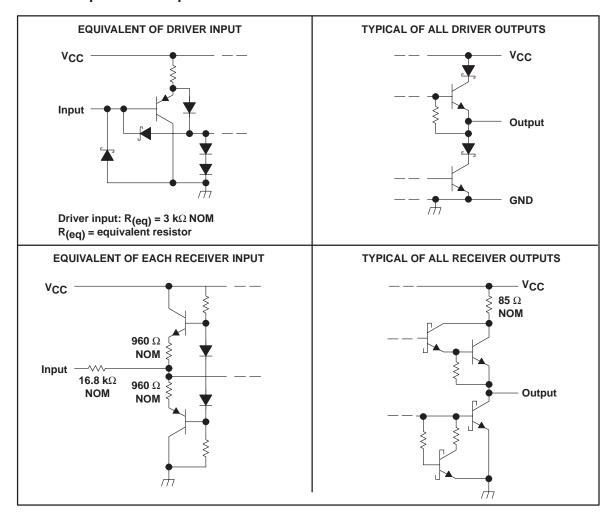


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematics of inputs and outputs





SN75179B DIFFERENTIAL DRIVER AND RECEIVER PAIR

SLLS003E - OCTOBER 1985 - REVISED JUNE 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	
Voltage range at any bus terminal	
Differential input voltage, V _{ID} (see Note 2)	±25\
Package thermal impedance, θ_{JA} (see Note 3): D package	197°C/V
P package	104°C/V
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

- NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.
 - 2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.
 - 3. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
High-level input voltage, VIH	Driver	2			V
Low-level input voltage, V _{IL}	Driver			0.8	V
Common-mode input voltage, V _{IC}		- 7‡		12	V
Differential input voltage, V _{ID}				±12	V
High-level input voltage, VIH Low-level input voltage, VIL Common-mode input voltage, VIC Differential input voltage, VID High-level output current, IOH Low-level output current, IOL	Driver			-60	mA
High-level output current, IOH	Receiver			-400	μА
Love lovel output output lov	Driver			60	A
Low-level output current, IOL	Driver Driver Receiver			8	mA
Operating free-air temperature, TA		0		70	°C

[‡] The algebraic convention, where the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	MIN	TYP†	MAX	UNIT
VIK	Input clamp voltage	I _I = -18 mA				-1.5	V
VO	Output voltage	IO = 0		0		6	V
V _{OD1}	Differential output voltage	I _O = 0		1.5		6	V
l V _{OD2} l	Differential output voltage	$R_L = 100 \Omega$	See Figure 1	1/2V _{OD1} or 2‡			٧
		$R_L = 54 \Omega$,	See Figure 1	1.5	2.5	5	V
V _{OD3}	Differential output voltage	See Note 4		1.5		5	V
△ V _{OD} I	Change in magnitude of common-mode output voltage§					±0.2	V
Voc	Common-mode output voltage	$R_L = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			3 -1	V
∆ Vocl	Change in magnitude of common-mode output voltage§					±0.2	V
IO	Output current	$V_{CC} = 0$,	$V_0 = -7 \text{ V to } 12 \text{ V}$			±100	μΑ
lН	High-level input current	V _I = 2.4 V				20	μΑ
IIL	Low-level input current	V _I = 0.4 V				-200	μΑ
laa	Chart aircuit autaut aurrent	$V_O = -7 V$			-250	mA	
los	Short-circuit output current	$V_O = V_{CC}$ or 12 V			250	IIIA	
ICC	Supply current (total package)	No load			57	70	mA

NOTE 4: See TIA/EIA-485-A, Figure 3.5, Test Termination Measurement 2.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	MIN	TYP	MAX	UNIT	
t _d (OD)	Differential output delay time	D: -54 O	See Figure 3		15	22	ns
t _t (OD)	Differential output transition time	$R_L = 54 \Omega$,	See Figure 3		20	30	ns

Symbol Equivalents

DATA-SHEET PARAMETER	TIA/EIA-422-B	TIA/EIA-485-A
Vo	V _{oa} , V _{ob}	V _{oa} , V _{ob}
VOD1	Vo	Vo
V _{OD2}	$V_t (R_L = 100 \Omega)$	$V_t (R_L = 54 \Omega)$
V _{OD3}		V _t (Test Termination Measurement 2)
Δ V _{OD}	$ V_t - \overline{V}_t $	$ V_t - \overline{V}_t $
Voc	V _{os}	V _{os}
Δ VOC	$ V_{OS} - \overline{V}_{OS} $	$ V_{OS} - \overline{V}_{OS} $
los	$ I_{sa} , I_{sb} $	
IO	_{xa} , _{xb}	l _{ia} , l _{ib}



[†] All typical values are at V_{CC} = 5 V and T_A = 25°C. ‡ The minimum V_{OD2} with 100- Ω load is either 1/2 V_{OD2} or 2 V, whichever is greater.

[§] Δ|V_{OD}| and Δ|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input changes from a high level to a low

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TE	ST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage	$V_0 = 2.7 V$,	$I_0 = -0.4 \text{ mA}$				0.2	V
VIT-	Negative-going input threshold voltage	$V_0 = 0.5 V$,	I _O = 8 mA		-0.2‡			V
V _{hys}	Hysteresis voltage (V _{IT+} – V _{IT-})					50		mV
Vон	High-level output voltage	$V_{ID} = 200 \text{ mV},$	$I_{OH} = -400 \mu A$,	See Figure 2	2.7			V
VOL	Low-level output voltage	$V_{ID} = -200 \text{ mV},$	$I_{OL} = 8 \text{ mA},$	See Figure 2			0.45	V
1.	Line input current	Other input at 0 V,	See Note 5	V _I = 12 V			1	mA
<u> </u>	Line input current	Other input at 0 V, See Note 5 $V_{\parallel} = -7 \text{ V}$					-0.8	IIIA
rį	Input resistance				12			kΩ
los	Short-circuit output current				-15		-85	mA
ICC	Supply current (total package)	No load	No load			57	70	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

NOTE 5: Refer to TIA/EIA-422-B for exact conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V},$		19	35	ns
^t PHL	Propagation delay time, high- to low-level output	C _L = 15 pF, See Figure 4		30	40	ns

PARAMETER MEASUREMENT INFORMATION

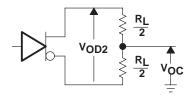


Figure 1. Driver V_{DD} and V_{OC}

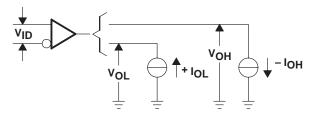
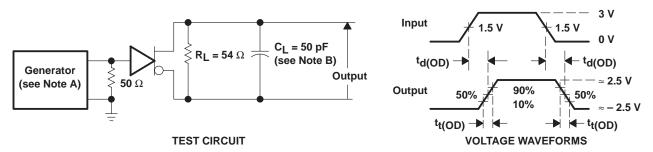


Figure 2. Receiver VOH and VOL

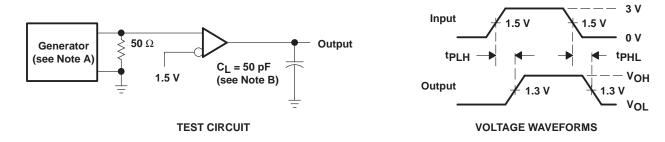
[‡] The algebraic convention, where the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

PARAMETER MEASUREMENT INFORMATION (CONTINUED)



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 6 ns, $t_f \le 6 \text{ ns}, Z_O = 50 \Omega.$
 - B. C_L includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_r \leq$ 6 ns, $t_f \le 6 \text{ ns}, Z_O = 50 \Omega.$
 - B. C₁ includes probe and jig capacitance.

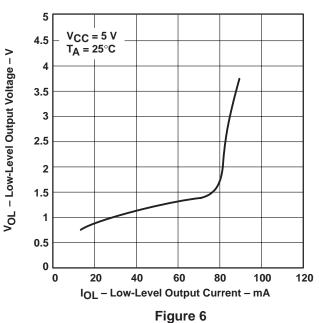
Figure 4. Receiver Test Circuit and Voltage Waveforms



TYPICAL CHARACTERISTICS

DRIVER **HIGH-LEVEL OUTPUT VOLTAGE** vs **HIGH-LEVEL OUTPUT CURRENT** 5 V_{CC} = 5 V 4.5 T_A = 25°C VOH − High-Level Output Voltage − V 4 3.5 3 2.5 2 1.5 1 0.5 0 0 - 20 -40-60- 80 -100-120IOH - High-Level Output Current - mA

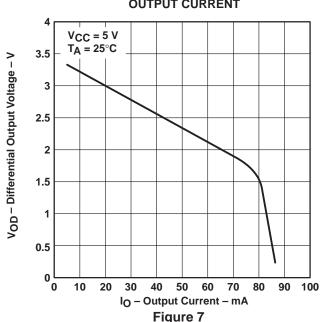
DRIVER
LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT



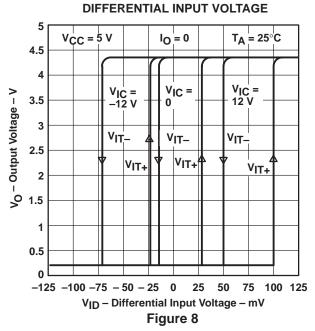
DRIVER

DIFFERENTIAL OUTPUT VOLTAGE
vs
OUTPUT CURRENT

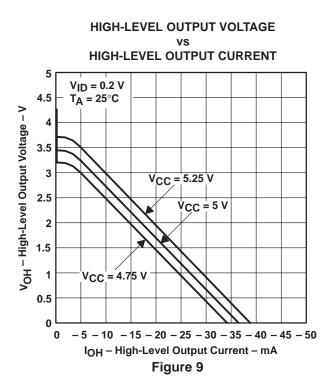
Figure 5

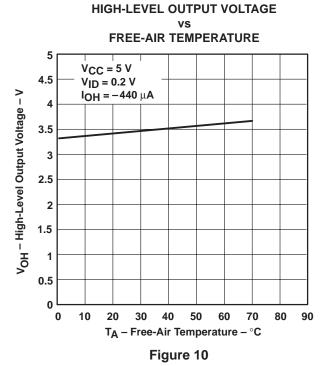


RECEIVER
OUTPUT VOLTAGE
VS



TYPICAL CHARACTERISTICS





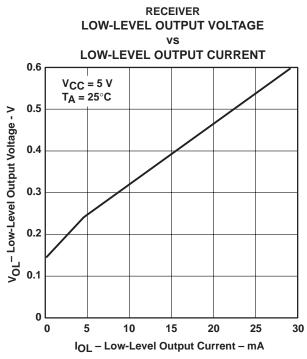
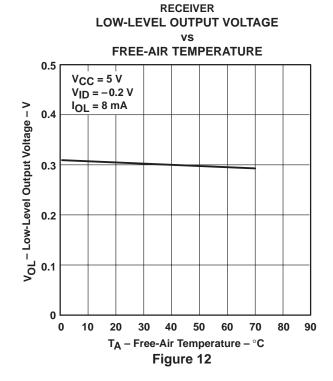


Figure 11







24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN75179BD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75179B	Samples
SN75179BDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75179B	Samples
SN75179BDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75179B	Samples
SN75179BDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75179B	Samples
SN75179BP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75179BP	Samples
SN75179BPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75179BP	Samples
SN75179BPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	A179B	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

24-Aug-2018

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

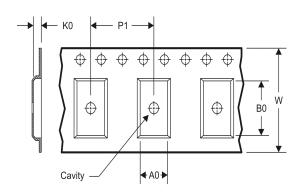
www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ŀ	SN75179BDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
I	SN75179BPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1

www.ti.com 14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75179BDR	SOIC	D	8	2500	340.5	338.1	20.6
SN75179BPSR	SO	PS	8	2000	367.0	367.0	38.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.